Flexibilisierung des Akkreditierungsbereiches gemäß der Anlage zur Akkreditierungsurkunde D-PL-12120-01-00

COSMIC SEMICONDUCTOR SOLUTIONS

Standort	Titel der Norm oder des Prüfverfahrens	Norm oder Prüfverfahren / aktueller Ausgabestand	Standard	Methode	aktueller Ausgabestand	flexibilisierte Ausgabestände	Flexibilisierung durchgeführt
Nördlingen	Failure mechanism based stress test qualification for integrated circuits in automotive applications	AEC-Q100 J1:2026	AEC-Q100		J1:2026	H J J1	012_2023 003_2026
Nördlingen	Basic environmental testing - Part 2-14: Tests. Test N: Change of temperature	IEC 60068 2-14 Ed.7.0 2023	IEC 60068	2-14	Ed.7.0 2023	Ed 5.0 Ed. 6.0 Ed.7.0	013_2016 004_2024
Nördlingen	Temperature cycling	JEDEC JESD22 A104 F01: 2023	JEDEC JESD22	A104	F01: 2023	E F F01	010_2020 006_2023
Nördlingen	Temperature cycling (air to air)	MIL-STD-750-1B 1051. 9	MIL-STD-750-1B	1051.	9	9	
Nördlingen	Temperature cycling	MIL-STD-883-1 1010. 9	MIL-STD-883-1	1010.	9	8 9	026_2016
Nördlingen	High-temperature life (non-operating)	MIL-STD-750-1B 1031. 5	MIL-STD-750-1B	1031.	5	5	
Nördlingen	Stabilization bake	MIL-STD-883-1 1008. 2	MIL-STD-883-1	1008.	2	2	
Nördlingen	High Temperature Storage Life (HTSL)	JEDEC JESD22 A103 E01: 2021	JEDEC JESD22	A103	E01: 2021	D E E01	001_2016 009_2021
Nördlingen	Discrete semiconductor components, hermetically sealed and die	ESA/SCC 5000 Issue 11 2026	ESA/SCC	5000	Issue 11 2026	Issue 6 Issue 7 Issue 8 Issue9 Issue 10 Issue 11	015_2017 002_2019 007_2020 001_2021 001_2026
Nördlingen	Integrated circuits: monolithic and multichip microcircuits wire-bonded, hermetically sealed and flip-chip monolithic microcircuits with non-organic substrate, hermetically and non-hermtically sealed and die	ESA/SCC 9000 Issue 13 2026	ESA/SCC	9000	Issue 13 2026	Issue 6 Issue 8 Issue 9 Issue 10 Issue 11 Issue 12 Issue 13	024_2016 016_2017 001_2018 002_2021 006_2024 002_2026
Nördlingen	Temperature, bias, and operating life	JEDEC JESD22 A108 G:2022	JEDEC JESD22	A108	G:2022	C D E F G	012_2016 002_2017 017_2017 012_2022
Nördlingen	Steady state life	MIL-STD-883-1 1005. 11	MIL-STD-883-1	1005.	11	9 10 11	029_2016 006_2017
Nördlingen	Burn-in test	MIL-STD-883-1 1015. 12	MIL-STD-883-1	1015.	12	10 11 12	061_2016 007_2017
Nördlingen	Steady - state operation life	MIL-STD-750-1B 1026. 5	MIL-STD-750-1B	1026.	5	5	
Nördlingen	Steady - state operation life (sample plan)	MIL-STD-750-1B 1027. 3	MIL-STD-750-1B	1027.	3	3	
Nördlingen	Steady state temperature humidity bias life test	JEDEC JESD22 A101 D01: 2021	JEDEC JESD22	A101	D01: 2021	C D D01	002_2016 003_2021
Nördlingen	Moisture resistance	MIL-STD-883-1 1004. 7	MIL-STD-883-1	1004.	7	7	
Nördlingen	Moisture resistance	MIL-STD-750-1B 1021. 4	MIL-STD-750-1B	1021.	4	3 4	007_2015
Nördlingen	Power and temperature cycling	JEDEC JESD22 A105 D: 2020	JEDEC JESD22	A105	D: 2020	C D	001_2020
Nördlingen	Accelerator moisture resistance - unbiased autoclave	JEDEC JESD22 A102 zurückgezogen	JEDEC JESD22	A102	zurückgezogen	D E	004_2016
Nördlingen	Highly accelerated temperature and humidity stress test (HAST)	JEDEC JESD22 A110 E01: 2021	JEDEC JESD22	A110	E01: 2021	D E E01	005_2016 008_2021
Nördlingen	Accelerated moisture resistance-unbiased HAST	JEDEC JESD22 A118 B01: 2021	JEDEC JESD22	A118	B01: 2021	A B B01	006_2016 005_2021
Nördlingen	Early life failure rate (ELFR)	AEC-Q100-008 - A:2003	AEC-Q100-008	-	A:2003	A	
Nördlingen	High-temperature (non-operating) life (sample plan)	MIL-STD-750-1B 1032. 2	MIL-STD-750-1B	1032.	2	2	
Nördlingen	Cycled temperature-humidity-bias with surface condensation life test	JEDEC JESD22 A100 E: 2020	JEDEC JESD22	A100	E: 2020	D E	008_2020
Nördlingen	Preconditioning of nonhermetic surface mount devices prior to reliability testing	JEDEC JESD22 A113 J:2026	JEDEC JESD22	A113	J:2026	F G H I J	004_2015 005_2017 006_2020 005_2026
Nördlingen	Low temperature storage life	JEDEC JESD22 A119 A:2015	JEDEC JESD22	A119	A:2015	- A	003_2015
Nördlingen	Moisture / reflow sensitivity classifications for non-hermetic surface mount devices	JEDEC J-STD-020 F:2022	JEDEC J-STD-020		F:2022	D01 E F	003_2023
Stuttgart	Preconditioning of nonhermetic surface mount devices prior to reliability testing	JEDEC JESD22 A113 J:2026	JEDEC JESD22	A113	J:2026	F G H I J	004_2015 004_2017 006_2020 006_2026
Stuttgart	Basic environmental testing - Part 2-14: Tests. Test N: Change of temperature	IEC 60068 2-14 Ed. 7.0 2023	IEC 60068	2-14	Ed. 7.0 2023	Ed 5.0 Ed. 6.0 Ed.7.0	013_2016 004_2024
Stuttgart	Solderability	JEDEC JESD22 B102 E: 2007	JEDEC JESD22	B102	E: 2007	D E	016_2016
Stuttgart	Solderability tests for component leads, terminations, lugs, terminals and wires	JEDEC J-STD-002 - E:2017	JEDEC J-STD-002	-	E:2017	D E	004_2020
Stuttgart	Failure analysis procedures for microcircuits	MIL-STD-883-5 5003.	MIL-STD-883-5	5003.		1	
Stuttgart	Destructive physical analysis (DPA)	MIL-STD-883-5 5009. zurückgezogen	MIL-STD-883-5	5009.	zurückgezogen	1 2	006_2022 008_2026
Stuttgart	External visual	MIL-STD-883-2 2009. 15	MIL-STD-883-2	2009.	15	11 12 13 14 15	035_2016 009_2017 005_2018 001_2022
Stuttgart	Radiography	MIL-STD-883-2 2012. 11	MIL-STD-883-2	2012.	11	9 10 11	010_2017 006_2018

Stuttgart	Moisture / reflow sensitivity classifications for non-hermetic surface mount devices	JEDEC J-STD-020 F:2022	JEDEC J-STD-020		F:2022	D01 E F	020_2016 004_2023
Stuttgart	Ultrasonic inspection of die attach	MIL-STD-883-2 2030. 2	MIL-STD-883-2	2030.	2	2	
Stuttgart	Application of scanning acoustic microscopy to plastic encapsulated devices	ESA/SCC 25200 Issue 4 2024	ESA/SCC	25200	Issue 4 2024	Issue 1 Issue 2 Issue 3 Issue 4	036_2016 007_2021 001_2024
Stuttgart	Internal visual (monolithic)	MIL-STD-883-2 2010. 14	MIL-STD-883-2	2010.	14	13 14	002_2014
Stuttgart	Internal visual inspection for DPA	MIL-STD-883-2 2013. 1	MIL-STD-883-2	2013.	1	1	
Stuttgart	Internal visual and mechanical	MIL-STD-883-2 2014.	MIL-STD-883-2	2014.			
Stuttgart	Internal visual (hybrid)	MIL-STD-883-2 2017. 14	MIL-STD-883-2	2017.	14	10 11 12 13 14	021_2016 011_2017 007_2018 002_2022
Stuttgart	Scanning electron microscope (SEM) inspection of metallization	MIL-STD-883-2 2018. 6	MIL-STD-883-2	2018.	6	6	
Stuttgart	Bond strength (destructive Bond Pull Test)	MIL-STD-883-2 2011. 10	MIL-STD-883-2	2011.	10	9 10	008_2018
Stuttgart	Nondestructive bond pull	MIL-STD-883-2 2023. 8	MIL-STD-883-2	2023.	8	7 8	003_2022
Stuttgart	Die shear strength	MIL-STD-883-2 2019. 11	MIL-STD-883-2	2019.	11	9 10 11	009_2018 004_2022
Stuttgart	Wire bond shear test method	JEDEC JESD22 B116 B: 2017	JEDEC JESD22	B116	B: 2017	A B	014_2017
Stuttgart	Solder ball shear test	AEC-Q100-010 A:2003	AEC-Q100-010		A:2003	A	
Stuttgart	Solder ball shear	JEDEC JESD22 B117 B: 2014	JEDEC JESD22	B117	B: 2014	A B	022_2016
Stuttgart	Environmental testing - Part 2-20: Tests - Test Ta and Tb: Test methods for solderability and resistance to soldering heat of devices with leads	IEC 60068 2-20 Ed. 6.0 2021	IEC 60068	2-20	Ed. 6.0 2021	Ed. 5.0 Ed. 6.0	011_2021
Stuttgart	Acoustic microscopy for non-hermetic encapsulated electronic components	JEDEC J-STD-035 A:2022	JEDEC J-STD-035		A:2022	- A	001_2023
Stuttgart	Die attach integrity	MIL-STD-750-2B 2017. 3	MIL-STD-750-2B	2017.	3	2 3	042_2016
Stuttgart	Solderability	MIL-STD-750-2B 2026. 14	MIL-STD-750-2B	2026.	14	11 12 13 14	043_2016 003_2020 009_2023
Stuttgart	Resistance to soldering heat	MIL-STD-750-2B 2031. 7	MIL-STD-750-2B	2031.	7	4 5 6 7	044_2016 009_2022 010_2023
Stuttgart	Bond strength (destructive bond pull test)	MIL-STD-750-2B 2037. 1	MIL-STD-750-2B	2037.	1	1	
Stuttgart	Visual inspection for unencapsulated semiconductor diode die	MIL-STD-750-2B 2073. 3	MIL-STD-750-2B	2073.	3	1 2 3	046_2016 007_2024
Stuttgart	Internal visual inspection (discrete semiconductor diodes)	MIL-STD-750-2B 2074. 7	MIL-STD-750-2B	2074.	7	4 6 7	047_2016 010_2022
Stuttgart	Radiography	MIL-STD-750-2B 2076. 7	MIL-STD-750-2B	2076.	7	3 5 6 7	048_2016 011_2022 007_2026
Stuttgart	Scanning electron microcope inspection of metallization	MIL-STD-750-2B 2077. 6	MIL-STD-750-2B	2077.	6	5	049_2016 011_2023
Stuttgart	Internal visual for wire bonded diodes/rectifiers	MIL-STD-750-2B 2078. 1	MIL-STD-750-2B	2078.	1	- 1	064_2016
Stuttgart	DPA procedures for diodes	MIL-STD-750-2B 2101. 5	MIL-STD-750-2B	2101.	5	3 4 5	050_2016 002_2018
Stuttgart	DPA procedures for wire bonded devices	MIL-STD-750-2B 2102. 2	MIL-STD-750-2B	2102.	2	- 1 2	051_2016 063_2016
Stuttgart	Solderability	MIL-STD-883-2 2003. 14	MIL-STD-883-2	2003.	14	10 11 12 13 14	001_2013 053_2016 012_2017 005_2022
Stuttgart	Plastic package opening for wire bond testing	AEC-Q100-Appendix 3 J:2023	AEC-Q100-Appendix 3		J:2023	H J	055_2016
Stuttgart	Failure mechanism based stress test qualification for integrated circuits in automotive applications	AEC-Q100 J1:2026	AEC-Q100		J1:2026	G H J J1	056_2016 013_2023 004_2026
Stuttgart	Wire bond shear test	AEC-Q100 001 C:1998	AEC-Q100	001	C:1998		
Stuttgart	Wire bond shear test	AEC-Q101-003 A:2005	AEC-Q101-003		A:2005	A	
Stuttgart	Hermetic seal	MIL-STD-750-1B 1071. 18	MIL-STD-750-1B	1071.	18	14 15 16 17 18	058_2016 062_2016 008_2022 005_2023
Stuttgart	External visual for non-transparent, glass-encased, double plug, noncavity, dial leaded diodes	MIL-STD-750-2B 2068. 1	MIL-STD-750-2B	2068.	1	- 1	003_2018
Stuttgart	Visual and mechanical examination	MIL-STD-750-2B 2071. 11	MIL-STD-750-2B	2071.	11	8 9 10 11	059_2016 004_2018 011_2025
Stuttgart	Temperature cycling (air to air)	MIL-STD-750-1B 1051. 9	MIL-STD-750-1B	1051.	9	9	
Stuttgart	Temperature cycling	MIL-STD-883-1 1010. 9	MIL-STD-883-1	1010.	9	9	
Stuttgart	Seal	MIL-STD-883-1 1014. 19	MIL-STD-883-1	1014.	19	15 16 17 18 19	013_2017 010_2018 012_2021 003_2024

Stuttgart	Counterfeit electrical, electronic, and electromechanical (EEE) parts: avoidance, detection, mitigation, and disposition - independent distribution	SAE AS6081 A:2023	SAE AS6081		A:2023	- A	008_2023
Stuttgart	Test methods standard; general requirements, suspect/counterfeit, electrical, electronic, and electromechanical parts	SAE AS6171 A:2018-04	SAE AS6171		A:2018-04	A	
Stuttgart	High reliability assembly for surface mount and through hole connections	ECSS-Q-70-61C 2022	ECSS-Q-70-61C		2022	2022	
Nördlingen	Qualification of power modules for use in power electronics converter units in motor vehicles	AQG 324 04.1_2021	AQG	324	04.1_2021	03.1 04.1	010_2025

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